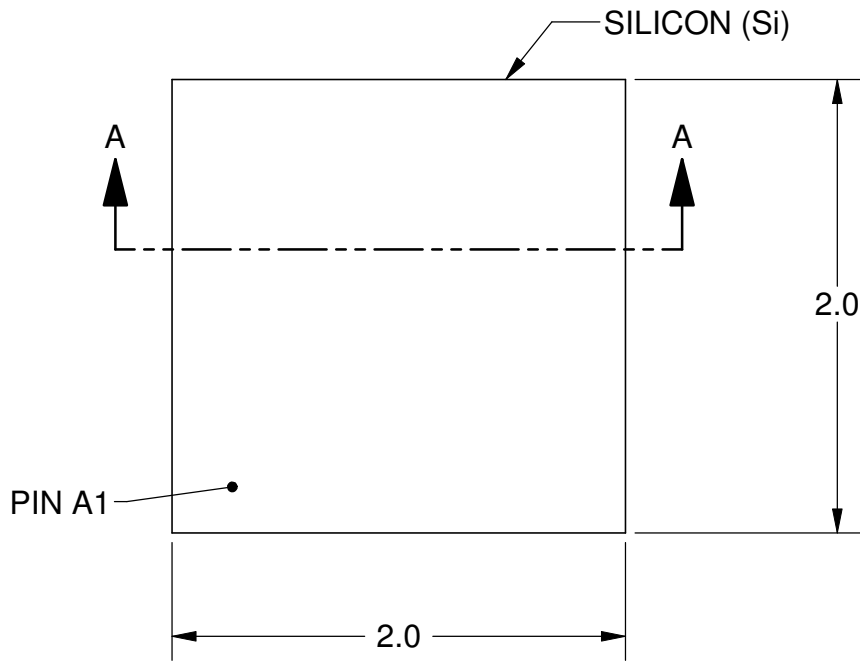
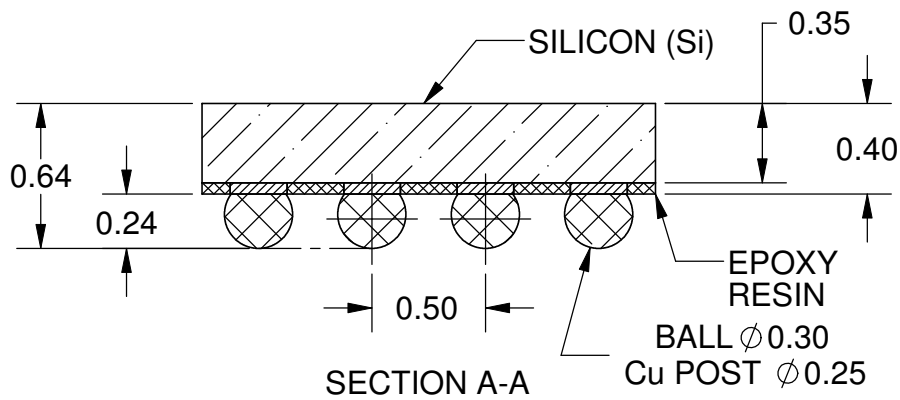
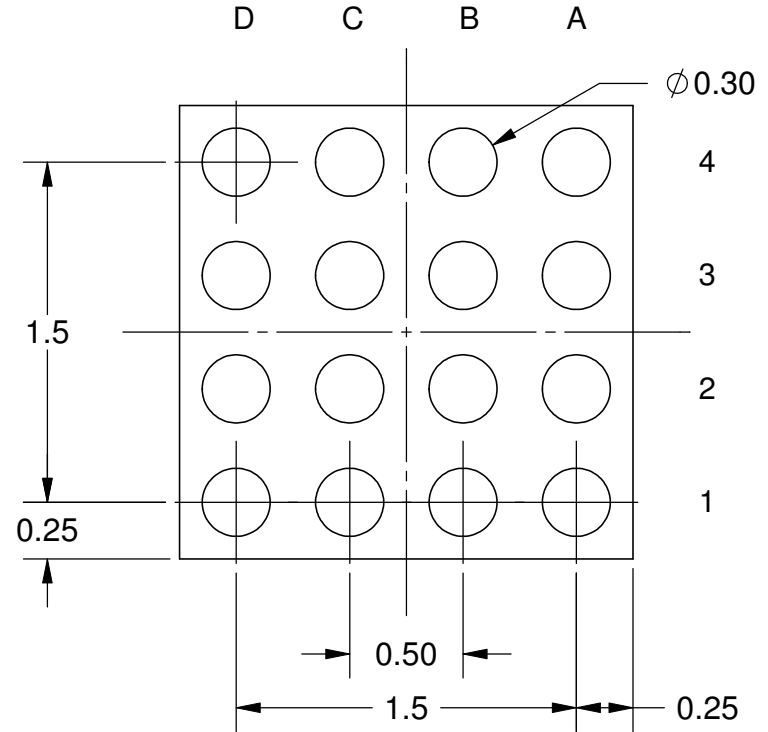


TOP VIEW



BALL VIEW




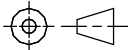
SECTION A-A

BALL $\phi 0.30$
Cu POST $\phi 0.25$

Notes: (Unless Otherwise Specified).

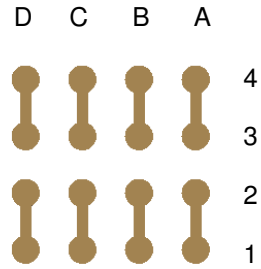
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.25mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP16T.5C-DC048D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP16T.5C1-DC048D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

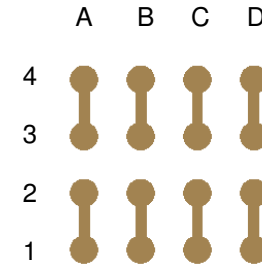
TOLERANCE UNLESS NOTED		APPROVALS		DATE						
X.X	+/- 0.3	DRAWN J. Hines		12/28/2010						TITLE
X.XX	+/- 0.03	ENG				WLP16T.5C-DC048D				
X.XXX	+/- 0.003	MFG				16-BALL P=0.5mm (TEG0510)				
ANGLES +/- 0.5°		THIRD ANGLE PROJECTION		SCALE		SIZE		DRAWING NO.		REV
ALL DIMENSIONS IN				30:1		A		550482		A
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		REVISED		DO NOT SCALE DRAWING				SHEET 1 OF 2		

DAISY CHAIN PATTERN

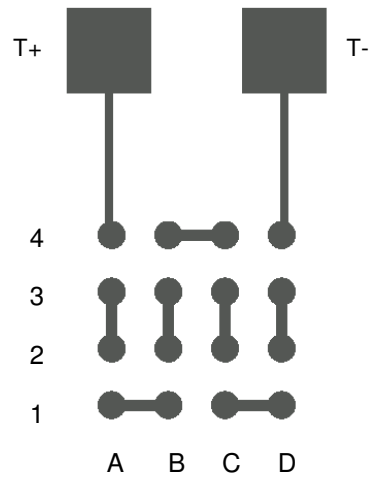
BALL VIEW



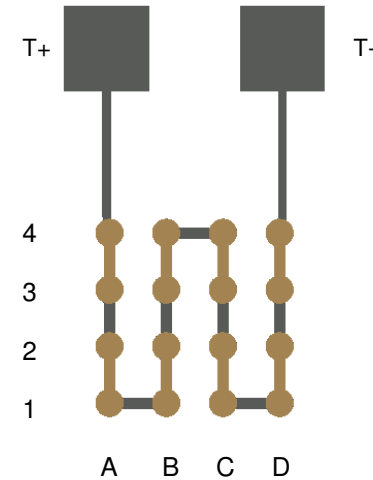
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.25mm (9.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine ®			
TITLE WLP16T.5C-DC048D 16-BALL P=0.5mm (TEG0510)			
SCALE 15:1	SIZE A	DRAWING NO. 550482	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	